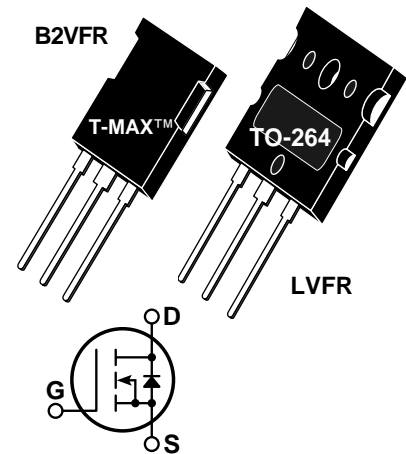


**POWER MOS V®**
**FREDFET**


Power MOS V® is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V® also achieves faster switching speeds through optimized gate layout.

- **Identical Specifications: T-MAX™ or TO-264 Package**
- **Lower Leakage**
- **Fast Recovery Body Diode**
- **Faster Switching**
- **100% Avalanche Tested**

**MAXIMUM RATINGS**

 All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT20M18	UNIT
$V_{DSS}$	Drain-Source Voltage	200	Volts
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$ ⑤	100	Amps
$I_{DM}$	Pulsed Drain Current ① ⑤	400	
$V_{GS}$	Gate-Source Voltage Continuous	±30	Volts
$V_{GSM}$	Gate-Source Voltage Transient	±40	
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	625	Watts
	Linear Derating Factor	5.0	W/°C
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	°C
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current ① ⑤ (Repetitive and Non-Repetitive)	100	Amps
$E_{AR}$	Repetitive Avalanche Energy ①	50	mJ
$E_{AS}$	Single Pulse Avalanche Energy ④	3000	

**STATIC ELECTRICAL CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0V, I_D = 250\mu\text{A}$ )	200			Volts
$I_{D(on)}$	On State Drain Current ② ⑤ ( $V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10V$ )	100			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② ( $V_{GS} = 10V, 0.5 I_{D[Cont.]}$ )			0.018	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = V_{DSS}, V_{GS} = 0V$ )			250	μA
	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}, V_{GS} = 0V, T_C = 125^\circ\text{C}$ )			1000	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30V, V_{DS} = 0V$ )			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}, I_D = 2.5mA$ )	2		4	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

**DYNAMIC CHARACTERISTICS**

**APT20M18 B2VFR - LVFR**

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V		9910		pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		2270		
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		650		
Q <sub>g</sub>	Total Gate Charge ③	V <sub>GS</sub> = 10V		330		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DD</sub> = 0.5 V <sub>DSS</sub>		75		
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		143		
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V		18		ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 0.5 V <sub>DSS</sub>		27		
t <sub>d(off)</sub>	Turn-off Delay Time	I <sub>D</sub> = I <sub>D</sub> [Cont.] @ 25°C		54		
t <sub>f</sub>	Fall Time	R <sub>G</sub> = 0.6Ω		6		

**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I <sub>S</sub>	Continuous Source Current (Body Diode)			100	Amps
I <sub>SM</sub>	Pulsed Source Current ① (Body Diode)			400	
V <sub>SD</sub>	Diode Forward Voltage ② (V <sub>GS</sub> = 0V, I <sub>S</sub> = -I <sub>D</sub> [Cont.])			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑥			5	V/ns
t <sub>rr</sub>	Reverse Recovery Time (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		230	ns
		T <sub>j</sub> = 125°C		450	
Q <sub>rr</sub>	Reverse Recovery Charge (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		0.9	μC
		T <sub>j</sub> = 125°C		3.4	
I <sub>RRM</sub>	Peak Recovery Current (I <sub>S</sub> = -I <sub>D</sub> [Cont.], di/dt = 100A/μs)	T <sub>j</sub> = 25°C		11	Amps
		T <sub>j</sub> = 125°C		20	

**THERMAL CHARACTERISTICS**

Symbol	Characteristic	MIN	TYP	MAX	UNIT
R <sub>θJC</sub>	Junction to Case			0.20	°C/W
R <sub>θJA</sub>	Junction to Ambient			40	

- ① Repetitive Rating: Pulse width limited by maximum T<sub>j</sub>
- ② Pulse Test: Pulse width < 380 μs, Duty Cycle < 2%
- ③ See MIL-STD-750 Method 3471

- ④ Starting T<sub>j</sub> = +25°C, L = 600μH, R<sub>G</sub> = 25Ω, Peak I<sub>L</sub> = 100A
- ⑤ The maximum current is limited by lead temperature.
- ⑥ I<sub>S</sub> ≤ I<sub>D</sub> [Cont.], di/dt = 100A/μs, V<sub>R</sub> = 50V, T<sub>j</sub> ≤ 150°C, R<sub>G</sub> = 2.0Ω

APT Reserves the right to change, without notice, the specifications and information contained herein.

